

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT2834274

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SENG KIM YE	04/28/2014
HONG WAN NG	04/28/2014
RECEIVING PARTY DATA	
Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 S. FEDERAL WAY, P.O. BOX 6
City:	BOISE
State/Country:	IDAHO
Postal Code:	83707-0006
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14264699
CORRESPONDENCE DATA	
Fax Number:	(206)359-4209
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	206-359-8000
Email:	swhelan@perkinscoie.com
Correspondent Name:	PERKINS COIE LLP - MICRON PATENT-SEA
Address Line 1:	PO BOX 1247
Address Line 4:	SEATTLE, WASHINGTON 98111-1247
ATTORNEY DOCKET NUMBER:	10829-9113.US00
NAME OF SUBMITTER:	STEPHEN P. WHELAN
SIGNATURE:	/Stephen P. Whelan/
DATE SIGNED:	04/29/2014
Total Attachments: 4	
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ASSIGNMENT BY INVENTORS

This Assignment is by the following individuals (the "Assignors"):

- Seng Kim Ye, having a mailing address of Block 311C, #05-32 Anchorvale Lane, Singapore 543311, Republic of Singapore; and
- Hong Wan Ng, having a mailing address of Block 75C, #24-76 Redhill Road, Singapore 153075, Republic of Singapore.

The Assignors invented one or more certain inventions (the "Invention(s)") described in an application for Letters Patent of the United States titled STACKED SEMICONDUCTOR DIE ASSEMBLIES WITH SUPPORT MEMBERS AND ASSOCIATED SYSTEMS AND METHODS, naming the Assignors as inventors, and filed on _____ as U.S. Application No. _____ (the "Application"). The Assignors authorize the Assignee, identified below, or its representatives to insert the application number and filing date of the Application when known.

Micron Technology, Inc., a corporation of Delaware having its principal place of business at 8000 S. Federal Way, P.O. Box 6, Boise, Idaho 83707-0006 ("Assignee"), desires to acquire the entire right, title and interest in and to the Invention(s) and the Application, and in and to any patents (collectively, "Patents") that may be granted for the Invention(s) in the United States or in any foreign countries.

For valuable consideration, the receipt and sufficiency of which Assignors acknowledge, Assignors hereby sell, assign, and transfer to Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to: the Invention(s), the Application, and any Patents; any divisions, continuations, and continuations-in-part of the Application and any other application claiming priority rights from the Application; any reissues, reexaminations, or extensions of any and all Patents; the right to file foreign applications directly in the name of Assignee; and the right to claim priority rights deriving from the Application (collectively, the "Rights"). Assignors warrant that Assignors own the Rights, and that the Rights are unencumbered. Assignors also agree to not sign any writing or do any act conflicting with this assignment, and, without further compensation, sign all documents and do



such additional acts as Assignee deems necessary or desirable to: perfect Assignee's enjoyment of the Rights; conduct proceedings regarding the Rights, including any litigation or interference proceedings; or perfect or defend title to the Rights. This Assignment may be executed in counterparts.



Date: 04/28/2014

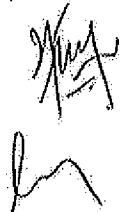


Seng Kim Ye


Witness to Signature by Seng Kim Ye:

Signature
Ong Yeow Chon
Printed Name

Signature
Tan Li Shan Shirley
Printed Name




Date: 4.29.2014



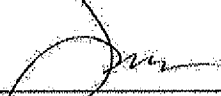
Hong Wan Ng

Witness to Signature by Hong Wan Ng:



Signature
Ong Yeow Chon

Printed Name



Signature
Tan Li Shan Shirley

Printed Name